



PTO/SB/08A (10-01)

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Sheet 1 of 4

Complete if Known

Application Number	10/782,270
Filing Date	February 18, 2004
First Named Inventor	Teck Kheng Lee
Group Art Unit	2815
Examiner Name	J. Clark
Attorney Docket Number	2269-4973.1US (00-0593.01/US)

U.S. PATENT DOCUMENTS					
Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
jbe		US - 3,239,496	03/1966	Jursich	
		US - 4,074,342	02/1978	Honn et al.	
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Examiner Initials *	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				
jbe		EP 0475022 A1	03/18/1992	Grube et al.		
		EP 684644	11/1995	Kata et al.		
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		EP 1009027	06/2000	Okuno		
jbe		KR 2001054744	07/2001	Choi et al. (English Abstract)		x

Examiner Signature	Jasmine Clark	Date Considered	01/20/05
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First Named Inventor	Teck Kheng Lee
Group Art Unit	2815
Examiner Name	J. Clark
Attorney Docket Number	2269-4973 IUS (00-0593 01/IUS)

NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
Jbe		AL-SARAWI et al., "A review of 3-D packaging technology," <i>Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging</i> , Vol 21, Issue 1, Feb. 1998, pp. 2-14.	
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Jbe		LI et al., "Stencil Printing Process Development for Flip Chip Interconnect," <i>IEEE Transactions Part C: Electronics Packaging Manufacturing</i> , Vol. 23, Issue 3, (July 2000), pp. 165-170.	

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		Group Art Unit	2815
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Sheet	4	of	4

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		Australian Search Report dated 11 Aug 2004 (3 pages).	
ylbe		Australian Search Report dated 16 Aug 2004 (4 pages).	

Examiner Signature	Jarmine Clark	Date Considered	01/20/05
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Group Art Unit	Unknown
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